

PECVD

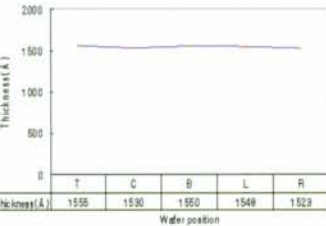
PES series



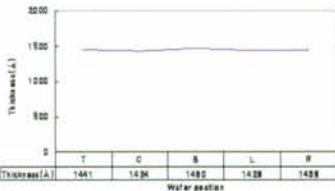
PECVD

Applications

- Poly silicon deposition
- Silicon oxide deposition
- Silicon nitride deposition
- Metal oxide deposition



- SiO₂ deposition
- Wafer size : 4"
- Average thickness : 1541.2Å
- Thickness uniformity : ±1.04%



- Si₃N₄ deposition
- Wafer size : 4"
- Average thickness : 1438.6Å
- Thickness uniformity : ±1.25%

Specifications

- Wafer size : 4inch, 6inch
- RF power : 1kW, 13,56MHz, Auto-matching type
- Substrate heater : Max, 500°C
- Loadlock chamber : Stand-alone type (option - Robot type)
- Ultimate pressure
 - Process chamber : $\leq 7 \times 10^{-6}$ Torr
 - Loadlock chamber : $\leq 5 \times 10^{-3}$ Torr
- Vacuum pump
 - Process chamber : TMP + Rotary pump
 - Loadlock chamber : Rotary pump
- Process control : Auto process control
- Dimension
 - Main system : 650mm(W) × 1680mm(D) × 1600mm(H)
 - Control rack : 620mm(W) × 700mm(D) × 1740mm(H)



Technology innovation
with advanced technology
We creat the future

Hightech Solution Corporation

ULTECH Co.,Ltd.

E vaporator

- Organic materials coating (OLED)
- Optical coating of rotational symmetry mirrors such as polygon mirrors
- Conventional materials coating
- Spintronix research (UHV & ultra low temperature system)



P lasma Immersion Ion Implanter (PIII)

- Ultra-shallow junction doping for sub-100nm CMOS
- Conformal doping of non-planar CMOS and other electronic devices
- Poly-silicon gate & trench sidewall doping
- Active matrix doping (LCD,PDP,AMOLED)



V ertical or horizontal type Furnace/LPCVD

- Low stress / Stoichiometric silicon nitride LPCVD
- Poly / Doped poly silicon LPCVD
- Silicon oxide LPCVD
- Wet / Dry oxidation
- Annealing
- LTO



S putter

- Magnetic thin films layer coating
- Opto-electronic films coating
- Industrial machinery & tools hard coating
- Conventional materials coating



D ry etcher (ICP,RIE)

- Nano etching
- Compound etching
- Polymer etching
- Bulk silicon deep etching



Major Product

R TP

- Thin Gate Oxidation(Low Pressure) (Nano device)
- Rapid Annealing(Atmospheric or Low Pressure)



S pray & Spin coater

- Uniform coating of topography such as V-grooves and trenches
- Photo resist coating
- Spin-On-Glass
- Organic materials



Axic, Inc.
493 Gianni Street
Santa Clara, 95054-2414
<http://www.axic.com/>

Represented in North America by: